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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10045895	FILING DATE 10/29/2001	CLASS 438	SUBCLASS	GAU 2823	EXAMINER
**APPLICANT'S: Park Stephen.					
**CONTINUING DATA VERIFIED: <i>Lee</i> THIS APPLICATION IS A CON OF 09/493,384 01/28/2000 PAT 6,355,555 <i>Yeo</i>					
NOTE-DISCLAIMER: The term of this patent shall not extend beyond the expiration date of Pat. No. <u>6,355,555</u>					
** FOREIGN APPLICATIONS VERIFIED: <i>Lee</i> <i>NONE</i>					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>			RESCIND <input type="checkbox"/>		
Foreign priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no			ATTORNEY DOCKET NO		
35 USC 119 conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no			2000.029996/TT3586C		
Verified and Acknowledged Examiners's initials <i>Lee</i>					
TITLE : Method of fabricating copper-based semiconductor devices using a sacrificial dielectric layer					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input checked="" type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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